

# 2SC5026G

## Silicon NPN epitaxial planar type

For low-frequency output amplification Complementary to 2SA1890G

#### ■ Features

- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- High collector-emitter voltage (Base open) V<sub>CEO</sub>
- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	80	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	80	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V	
Collector current	I <sub>C</sub>	1	A	
Peak collector current	I <sub>CP</sub>	1.5	A	
Collector power dissipation *	P <sub>C</sub>	1	W	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

Note) \*: Copper plate at the collector is more than 1 cm $^2$  in area, 1.7 mm in thickness Absolute maximum rating without heat sink for  $P_C$  is 0.5 W

## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = 10 \mu\text{A}, I_E = 0$	80			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 1 \text{ mA}, I_B = 0$	80			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_E = 10 \mu\text{A}, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 40 \text{ V}, I_E = 0$			0.1	μΑ
Forward current transfer ratio	h <sub>FE1</sub> *2	$V_{CE} = 2 \text{ V}, I_{C} = 100 \text{ mA}$	120		340	_
	h <sub>FE2</sub> *1	$V_{CE} = 2 \text{ V}, I_{C} = 500 \text{ mA}$	60			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.15	0.3	V
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.85	1.2	V
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		10	20	pF
(Common base, input open circuited)						

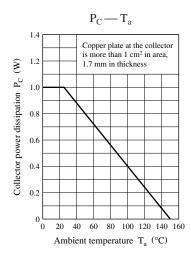
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

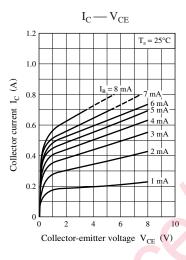
- 2. \*1: Pulse measurement
  - \*2: Rank classification

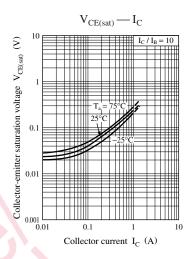
Rank	R	S
h <sub>FE1</sub>	120 to 240	170 to 340

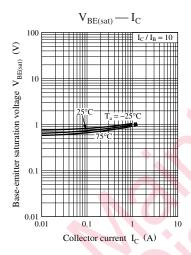
### ■ Package

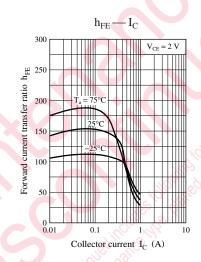
- Code MiniP3-F2
- Pin Name
  - 1: Base
  - 2: Collector
- 3: Emitter
- Marking Symbol: 2A

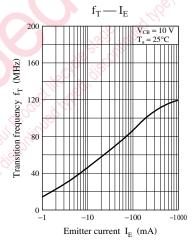


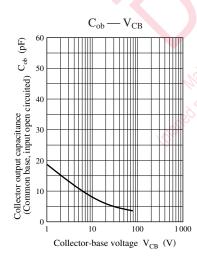






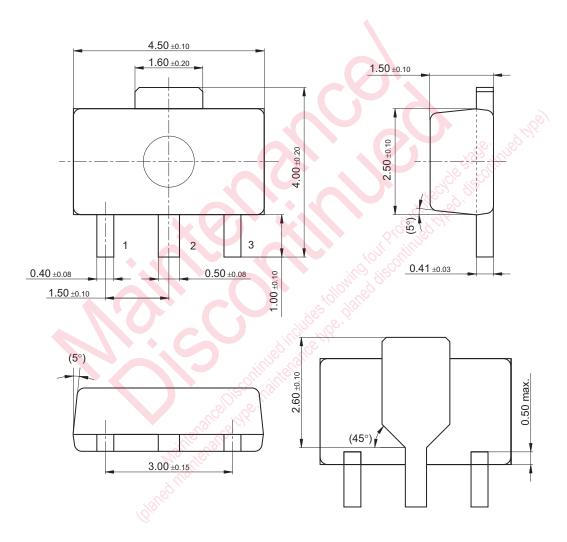






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MiniP3-F2 Unit: mm



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